

Board description

iSSI30R12H

Infineon's coreless-transformer advanced solid-state isolator (Infineon SSI)

About this document

This user guide describes the functionalities and key features of Infineon's coreless-transformer advanced solid-state isolator.

Scope and purpose

The Infineon SSI solid-state isolator evaluation board EVAL-iSSI30R12H features the coreless-transformer advanced solid-state isolator, iSSI30R12H. This user guide covers the design revision 1.2 of this evaluation board.

iSSI30R12H is certified as per UL 1577 and reinforced isolation (IEC 60747-17, planned).

Intended audience

- Engineers who want to learn how to use Infineon's SSI solid-state isolator iSSI30R12H
- Experienced design engineers who design circuits with photovoltaic isolators (PVI), IGBTs, and MOSFETs
 MOSFET
- Design engineers who develop solid-state relays

Evaluation board

The evaluation board EVAL-iSSI30R12H is designed based on environmental conditions described in this document. It has been tested as described in this document, but not qualified regarding manufacturing, lifetime, or over the full range of ambient operating conditions. The boards provided by Infineon are not subject to full production tests.

Evaluation boards are not subject to the same procedures as regular products regarding returned material analysis (RMA), process change notification (PCN), and product discontinuation (PD). Evaluation boards are intended to be used under laboratory conditions and by trained specialists only.

Note: The printed circuit board (PCB) and auxiliary circuits are NOT optimized for final customer design.

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Important notice



Important notice

User Guide

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Safety precautions



Safety precautions

Note: Please note the following warnings regarding the hazards associated with development systems

Table 1 Safety precautions



Warning: The DC link potential of this board is up to 1000 VDC. When measuring voltage waveforms by oscilloscope, high voltage differential probes must be used. Failure to do so may result in personal injury or death.



Warning: The evaluation or reference board is connected to the grid input during testing. Hence, high-voltage differential probes must be used when measuring voltage waveforms by oscilloscope. Failure to do so may result in personal injury or death. Darkened display LEDs are not an indication that capacitors have discharged to safe voltage levels.



Caution: The heat sink and device surfaces of the evaluation or reference board may become hot during testing. Hence, necessary precautions are required while handling the board. Failure to comply may cause injury.



Caution: Only personnel familiar with the drive, power electronics and associated machinery should plan, install, commission and subsequently service the system. Failure to comply may result in personal injury and/or equipment damage.



Caution: The evaluation or reference board contains parts and assemblies sensitive to electrostatic discharge (ESD). Electrostatic control precautions are required when installing, testing, servicing or repairing the assembly. Component damage may result if ESD control procedures are not followed. If you are not familiar with electrostatic control procedures, refer to the applicable ESD protection handbooks and guidelines.



Caution: An evaluation board that is incorrectly applied or installed can lead to component damage or reduction in product lifetime. Wiring or application errors such as undersizing the load, supplying an incorrect or inadequate AC supply, or excessive ambient temperatures may result in system malfunction.



Caution: The evaluation or reference board is shipped with packing materials that need to be removed prior to installation. Failure to remove all packing materials that are unnecessary for system installation may result in overheating or abnormal operating conditions.

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1 Overview and key features

EVAL-iSSI30R12H is intended for evaluating the product features of Infineon's SSI solid-state isolator, iSSI30R12H, in an application circuit. The key features of the board and the iSSI30R12H are as follows:

- Evaluation board with iSSI30R12H and two CoolMOS™ IPT60T022S7 MOSFETs in an AC switch configuration
- Ultra-fast overcurrent detection that is triggered at the typical peak current of 35 A
- Direct-chip temperature measurement of CoolMOS™ with shutdown at 155°C
- Fast turn-on
- Fast turn-off after overcurrent and over-temperature protection
- Dynamic Miller clamping

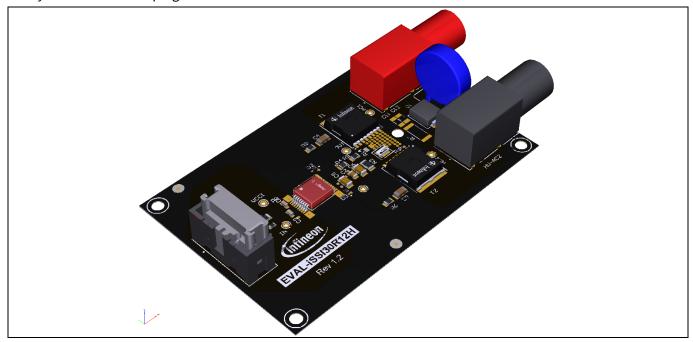


Figure 1 The EVAL-iSSI30R12H board

This board is best suited for testing switching, as described in Chapter 3. It requires additional considerations about thermal and power balance for continuous operation.

The control interface can be connected to a pulse generator, a microcontroller, or other digital circuits with appropriate driving capability of at least 25 mA.

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2 Absolute maximum ratings, operating conditions, and supply voltages

Some components on the evaluation boards as well as the Infineon SSI solid-state isolator have defined operating conditions and maximum ratings to avoid damage to individual parts and the overall evaluation board.

Table 2 Absolute maximum ratings

| Pin/parameter name | Connector | Min | Max | Unit | Note |
|-----------------------------------|------------------|------|-----|------|--|
| VSUP | X2.1, X2.2 | -10 | 3.6 | V | Input, Infineon SSI solid-state isolator voltage supply |
| INP | X2.5, X2.6 | -10 | 15 | V | Input, digital signal |
| HV-AC1 HV-AC2 | HV-AC1 HV-AC2 | -320 | 320 | V | Input, high-voltage power supply. For 42 V and above, special high-voltage lab environment is strongly recommended |
| AC-15 RMS current | HV-AC1/2 | - | 2 | Α | |
| RMS current | HV-AC1/2 | - | 7 | А | |
| DC current | HV-AC1/2 | - | 7 | Α | |
| AC1 peak current AC2 peak current | HV-AC1 HV-AC2 | - | 45 | А | Phase peak current for overcurrent protection test ($t_{pulse} < 20 \mu s$) |
| $f_{\sf sw}$ | | - | 1 | Hz | Maximum switching frequency for continuous operation. Power dissipation required for power transistor and Infineon SSI solidstate isolator has been carefully considered |

The printed circuit board (PCB) assembly is optimized for a *VSUP* voltage supply of 3.3 V. Higher supply voltages may require adjustments to the current limiting resistor, R1.

Table 3 Operating conditions and supply voltages

| Pin name | Min. | Тур. | Max. | Unit | Note |
|----------|------|------|------|------|-----------------------|
| VSUP | 2.5 | 3.3 | 3.5 | ٧ | Input voltage supply |
| INP | 0 | - | 3.3 | ٧ | Input, digital signal |
| HV-AC1 | -320 | - | 320 | | |



3 Getting started with EVAL-iSSI30R12H

Follow the steps given in this chapter to set up and power up the board, and to perform initial evaluations.

Prerequisites

- Have a low-voltage supply ready for the input supply voltage, VSUP, with a current capability of at least 25 mA for VSUP
- Have a power supply, V_{HV}, in series with a suitable load, Z_{Load}, ready to connect HV-AC1 and HV-AC2
- Have a function generator ready for control signal input, INP

To adapt the circuit to application requirements, resistor or capacitor values can be changed to optimize performance.

Steps to power up the board

- 1. Connect the supply voltage, VSUP, to connector X2.1 with +3.3 V and the ground, GND, to connector X2.7.
- 2. Connect the digital pulse-width modulation (PWM) generator to input signal connector *X*2.5 and *GND* to connector *X*2.9. Make sure that the outputs of the PWM generator are disabled, or the signals are set to low.
- 3. Connect the power supply, V_{HV}, to connector *HV-AC1*.
- 4. Connect the ground of power supply, V_{HV}, to one end of the load, Z_{Load}, and the other end to connector *HV-AC2*.
- 5. The board is now ready to evaluate switching.

Steps to safely power down the board

- 1. Turn off the power supply, V_{HV} .
- 2. Discharge the DC-link capacitor (if available) and check the DC-link voltage with, e.g., a digital multimeter or an oscilloscope (for DC operation).
- 3. Turn off the low-voltage supply.

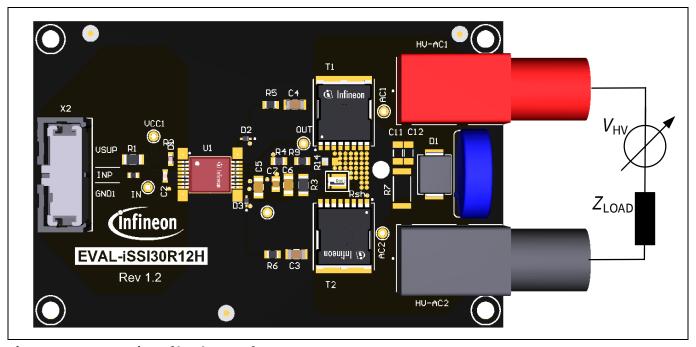


Figure 2 Connection of load, Z_{Load}, for tests



3.1 Overcurrent protection

The detection circuit monitors the voltage across shunt resistor, Rsh. This signal passes a noise RC filter, consisting of R3 and C6. The integrated comparator of the Infineon SSI compares it to a fixed threshold voltage $|V_{CS,th}|$ at terminal CS of iSSI30R12H. The maximum peak current can be adapted to application requirements by changing the shunt resistor, Rsh, using the following equation:

$$Rsh = \frac{V_{\rm CS,th}}{I_{\rm pk,max}}$$

Once triggered, the protection reacts quickly and is able to turn off, for example, CoolMOS™ IPT60T022S7 in a very short time. Thus, it is able to support AC-15 system tests as per IEC 60947-5-1 guidelines under appropriate operating conditions.

The triggering of overcurrent protection leads to the latched turn-off of the power switch with a sinking current, $I_{\text{off, fast, sat.}}$. To return to normal operation, applying either 0 V to VSUP or a low signal at the logic control input, INP, is required.

3.2 Over-temperature protection

iSSI30R12H provides a constant bias current, $I_{TS,bias}$, for temperature sense diodes inside CoolMOS[™] IPT60T022S7. The constant current generates a temperature-dependent forward voltage at the diodes. The diode voltage is connected to the terminal, TS, and the terminal voltage is compared to the threshold voltage $V_{TS,th}$. The integrated comparator includes a noise filter of duration $t_{TS,filter}$ for safely detecting the sensor signal. This noise filter is be complemented by an external RC filter (R4, C7).

Once triggered, the protection reacts quickly and is able to turn off, for example, CoolMOSTM IPT60T022S7 in a very short time. The triggering of the over-temperature protection leads to the latched turn-off of the power switch with a sinking current of $I_{\text{off, fast, sat}}$. To return to normal operation, applying either 0 V to VSUP or a low signal at the logic control input, INP, is required.

The triggering of the over-temperature protection can be forced by externally heating of the temperature sensor.

3.3 Connectors and pin assignment

Table 4 Connectors and pin assignment

| Connector | Pin | Marking/ function | Note |
|-----------|-----------------------------------|----------------------|---|
| X2 | 1, 2, 3, 4 5, 6 7, 8, 9, 10 | VSUP INP GND1 | Infineon SSI solid-state isolator voltage supply Infineon SSI solid-state isolator input signal /INF Infineon SSI solid-state isolator voltage supply reference |
| HV-AC1 | 1 | HV-AC1 | High-voltage power supply |
| HV-AC2 | 1 | HV-AC2 | |

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3.4 Board options

The evaluation board offer a few functional options implemented by parts that are not populated. These options are:

- Realization of a snubber circuit (C11, C12, R7)
- Using a PTC resistor R14 instead of the on-chip temperature sense of IPT60T022S7. This option requires the following actions:
 - o depopulate R9,
 - o populate a suitable PTC resistor at footprint R14 and
 - o exchange iSSI30R12H by part number iSSI30R11H.



4 Schematic diagram

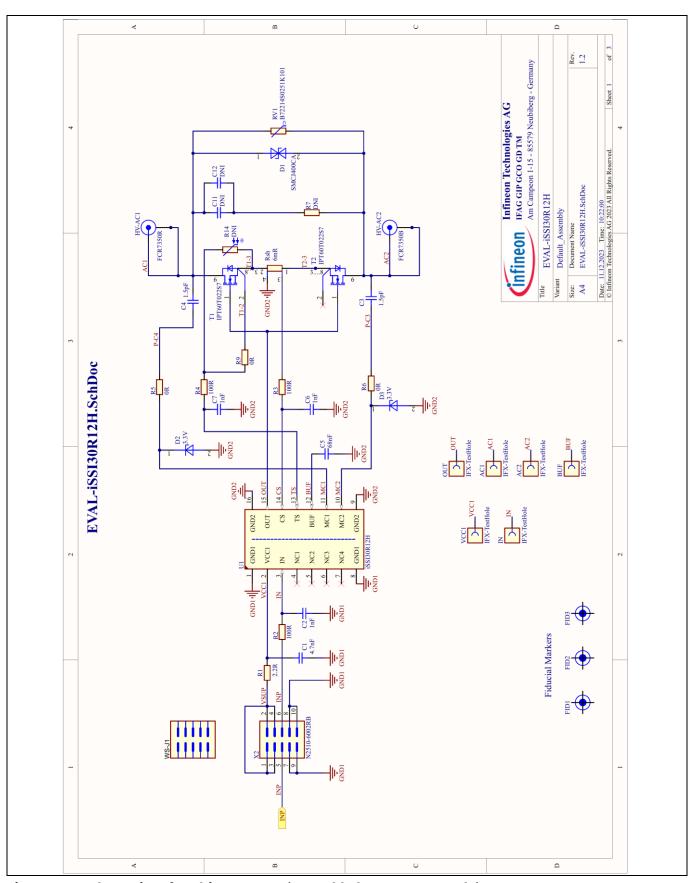


Figure 3 Schematics of Eval-iSSI30R12H (assembled components only)



5 Layout

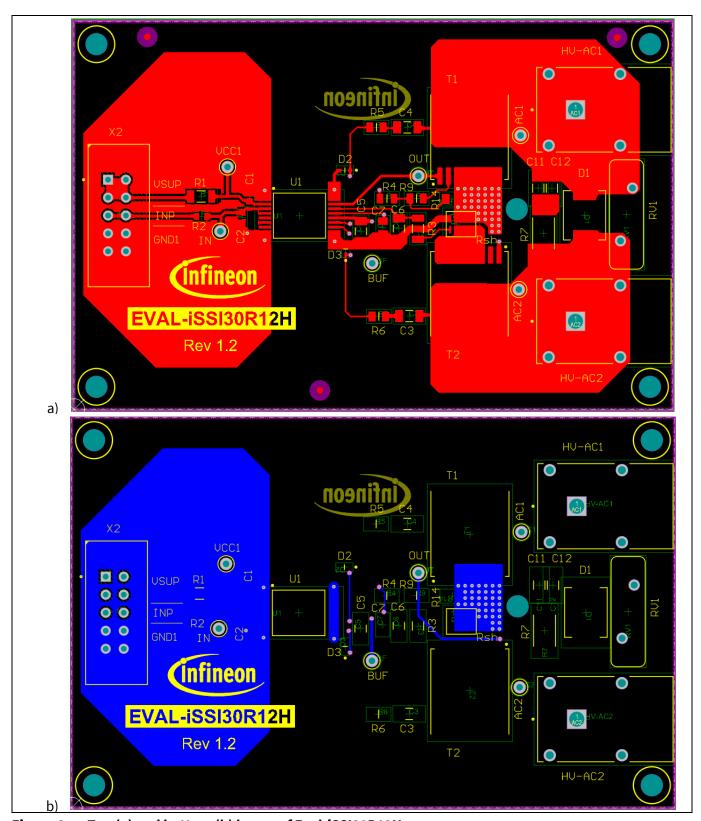


Figure 4 Top (a) and bottom (b) layers of Eval-iSSI30R12H

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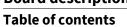


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Table 5 **Eval-iSSI30R12H bill of materials**

| Component | Quantity | Description | Manufacturer | Part number |
|-----------|---|---|--|-------------------|
| C1 | 1 | CAP / CERA / 4.7nF / 25V / 10% / X7R (EIA) / -55°C to 125°C / 0603(1608) / SMD / - | MuRata | GRM188R71E472KA01 |
| C2 | 1 | CAP / CERA / 1nF / 50V / 10% / X7R (EIA) / -55°C to 125°C / 0603(1608) / SMD / - | Wurth Elektronik | 885012206083' |
| C3, C4 | 2 | CAP / CERA / 1.5pF / 2kV / 0.1% / COG (EIA) / NPO / -55°C to 125°C / 3.20mm L X 1.60mm W X 0.9mm H / SMD / - | Walsin | 1206N1R5B202CT |
| C5 | 1 | CAP / CERA / 68nF / 50V / 10% / X7R (EIA) / -55°C to 125°C / 1206(3216) / SMD / - | MuRata | GRM319R71H683KA01 |
| C6 | 1 | CAP / CERA / 1nF / 50V / 10% / X7R (EIA) / -55°C to 125°C / 1206(3216) / SMD / - | MuRata | GRM319R71H102KA01 |
| C7 | 1 | CAP / CERA / 1nF / 50V / 10% / X7R (EIA) / -55°C to 125°C / 0805(2012) / SMD / - | MuRata | GCM216R71H102KA37 |
| D1 | 1 | TVS Diodes | Littelfuse | SMCJ400CA |
| D2, D3 | 2 | DIODE ZENER 3.3V 500MW SOD523 | ON Semiconductor | SZMM5Z3V3T1G |
| HV-AC1 | 1 | Banana Test Connector, 4mm, Socket, PCB Mount, 24 A, 1 kV, Gold Plated Contacts, Red | Cliff ELectronics Component Linited | FCR7350R |
| HV-AC2 | 1 | Banana Test Connector, 4mm, Socket, PCB Mount, 24 A, 1 kV, Gold Plated Contacts, Black | Cliff ELectronics Component Linited | FCR7350B |
| R1 | 1 RES / STD / 2.2R / 250mW / / 100ppm/K / -55°C to 155°C 1206(3216) / SMD / - | | Vishay | CRCW12062R20FK |
| R2 | 1 | RES / STD / 100R / 100mW / 1% / 100ppm/K / -55°C to 155°C / 0603(1608) / SMD / - | Vishay | CRCW0603100RFK |
| R3 | 1 | RES / STD / 100R / 250mW / 1% / 100ppm/K / -55°C to 155°C / 1206(3216) / SMD / - | Vishay | CRCW1206100RFK |
| R4 | 1 | RES / STD / 100R / 125mW / 1% / 100ppm/K / -55°C to 155°C / 0805(2012) / SMD / - | Vishay | CRCW0805100RFK |

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| Component | Quantity | Description | Manufacturer | Part number |
|---|----------|---|--------------------------|----------------------------|
| R5, R6, R9 | 3 | RES / - / 0R / 125mW / - / - / - / 0805(2012) / SMD / - | Multicomp | MCMR08X000 PTL |
| Rsh | 1 | RES / STD / 6mR / 1W / 1% / 75ppm/K / -55°C to 155°C / 1206(3216) / SMD / - | Susumu | KRL3216T4A-M-R006-F- T1 |
| RV1 | 1 | RES / STD / - / - / - / - / - 40°C to 105°C / 7.50mm C X 0.80mm W 15.50mm L X 4.80mm T X 18.50mm H / THT / - | TDK Corporation | B72214S0251K101 |
| T1, T2 | 2 | MOSFET 600V, 22 mΩ CoolMOS™ S7 Power Device with temperature sensor | Infineon Technologies | IPT60T022S7 |
| U1 | 1 | Coreless-Transformer Advanced Solid-State Isolators | Infineon Technologies | iSSI30R12H |
| WS-J1 | 1 | Wiremount Socket, 100mil, 5x2, Gray | 3M | 3473-6600 |
| X2 1 Header, 4-Wall Lo-PRO, .100, Straight, 10Pins, 2.54mm Pitcl | | 3M | N2510-6002RB | |

Board description

Revision history



Revision history

| Document revision | Date | Description of changes |
|-------------------|------------|---|
| 1.0 | 2023.12.19 | Initial version |
| 1.20 | 2024.02.12 | Updated to revision 1.20 (footer) |
| 1.30 | 2024.08.01 | Updating UL 1577 certification status |
| 1.30 | 2024.08.01 | Replacing term "iSSI" with "Infineon SSI" |

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